

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2024/0179868 A1

Sathyamurthy et al.

May 30, 2024 (43) **Pub. Date:**

(54) INTEGRATION OF ACTIVE MEMS COOLING SYSTEMS INTO THIN COMPUTING DEVICES

(71) Applicant: Frore Systems Inc., San Jose, CA (US)

(72) Inventors: Prabhu Sathyamurthy, San Jose, CA (US); Suryaprakash Ganti, Los Altos, CA (US); Seshagiri Rao Madhavapeddy, La Jolla, CA (US); Nilesh Sudhir Hasabnis, Fremont, CA (US); Vikram Mukundan, San Ramon, CA (US); William Finn Ninian Paisley, Los Altos Hills, CA (US)

(21) Appl. No.: 18/523,790

(22) Filed: Nov. 29, 2023

Related U.S. Application Data

Provisional application No. 63/429,133, filed on Nov. 30, 2022, provisional application No. 63/547,653, filed on Nov. 7, 2023.

Publication Classification

(51) Int. Cl. H05K 7/20 (2006.01)G06F 1/20 (2006.01)

U.S. Cl. CPC H05K 7/20172 (2013.01); G06F 1/20 (2013.01); H05K 7/20145 (2013.01); H05K 7/20154 (2013.01); H05K 7/20436 (2013.01)

(57)ABSTRACT

A cooling system for a computing device is described. The cooling system includes a heat transfer structure. The heat transfer structure includes a heat spreader, a fin structure, and a differential pressure device. The fin structure transfers heat from the heat spreader to a fluid. The differential pressure device generates a low pressure region that draws the fluid from an ingress in the computing device through the fin structure. The heat transfer structure is enclosed in a chamber of the computing device. The chamber includes the ingress and an egress.

